

ABSTRACT

An ink jet printhead chip that is manufactured in accordance with an integrated circuit fabrication technique includes a wafer substrate that defines a plurality of nozzle chambers as a result of an etching process. An etch stop layer is positioned on a front side of the wafer substrate so that portions of the etch stop layer define a roof wall for each nozzle chamber, each said portion defining at least one ink ejection port, also a result of an etching process carried out on each portion. A plurality of actuators are arranged on a back side of the wafer substrate, each actuator being operatively positioned relative to each respective nozzle chamber to eject ink from the nozzle chambers.

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